

SOT814-1

plastic thermal enhanced thin shrink small outline package/
transparent; no leads; 16 terminals; body 6.6 x 5.2 x 1.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSON16T
Package type industry code	HTSSON16T
Package style descriptive code	HTSSON (thermal enhanced thin shrink small outline; no leads)
Package style suffix code	T (transparent)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-11-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.1	-	5.2	5.3	mm
E	package width	6.5	-	6.6	6.7	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	[tbd]	-	1.1	[tbd]	mm
n ₂	actual quantity of termination	-	-	16	-	

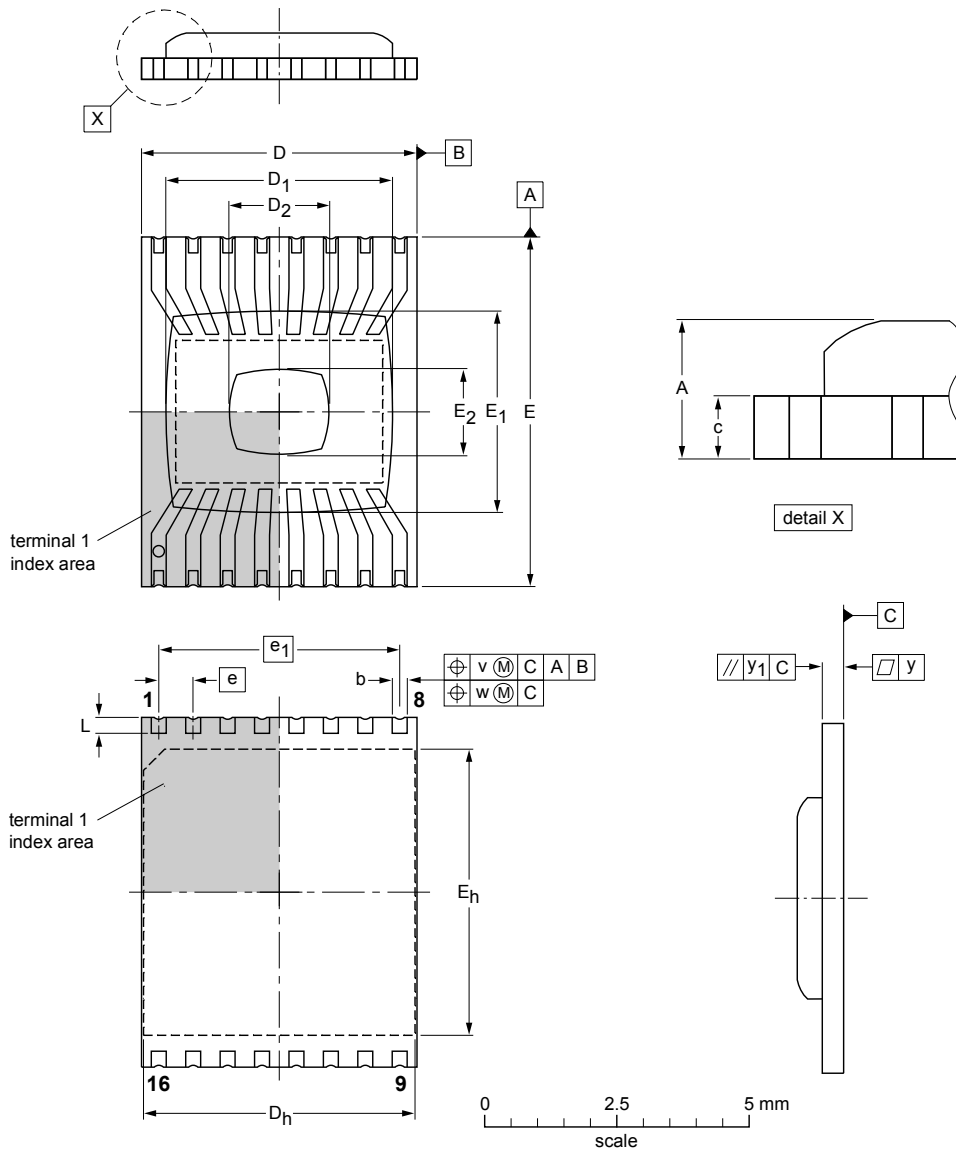


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2. Package outline

HTSSON16T: plastic thermal enhanced thin shrink small outline package/transparent; no leads; 16 terminals; body 6.6 x 5.2 x 1.1 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	b	c	D	D ₁	D ₂ min.	D _h	E	E ₁	E ₂ min.	E _h	e	e ₁	L	v	w	y	y ₁
mm	1.1	0.33 0.23	0.5 0.3	5.3 5.1	4.5 4.0	1.50	5.15 4.95	6.7 6.5	4.2 3.7	1.00	5.4 5.2	0.65	4.55	0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT814-1	---	---	---			03-10-10 03-11-19

Fig. 1. Package outline HTSSON16T (SOT814-1)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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